

Title (en)  
HOT-DIP GALVANIZED STEEL SHEET HAVING HIGH STRENGTH AND ALSO BEING EXCELLENT IN FORMABILITY AND GALVANIZING PROPERTY

Title (de)  
HEISSGETAUCHTES GALVANISIERTES STAHLBLECH MIT HOHER FESTIGKEIT UND HERVORRAGENDEN EIGENSCHAFTEN BEIM UMFORMEN UND GALVANISIEREN

Title (fr)  
TOLE D'ACIER GALVANISEE PAR IMMERSION A CHAUD PRESENTANT DE BONNES QUALITES DE RESISTANCE, DE FORMABILITE ET DE GALVANISATION

Publication  
**EP 1146132 A4 20020605 (EN)**

Application  
**EP 00966468 A 20001013**

Priority

- JP 0007115 W 20001013
- JP 30073999 A 19991022
- JP 2000211028 A 20000712

Abstract (en)  
[origin: EP1146132A1] A hot-dip galvanized high-strength steel sheet having superior workability and galvanizability containing: 0.01% to 0.20% by weight of C; 1.0% by weight or less of Si; more than 1.5% to 3.0% by weight of Mn; 0.10% by weight or less of P; 0.05% by weight or less of S; 0.10% by weight or less of Al; 0.010% by weight or less of N; 0.010% to 1.0% by weight in total of at least one element selected from the group consisting of Ti, Nb, and V; and the balance being Fe and incidental impurities; in which the steel sheet has the metal structure in which the areal rate of the ferrite phase is 50% or more, the ferrite phase has an average grain diameter of 10  $\mu$ m or less, and the thickness of a band-like structure composed of the second phase satisfies the relationship  $T_b/T \leq 0.005$ , where  $T_b$  is the average thickness in the sheet thickness direction of the band-like structure and  $T$  is the thickness of the steel sheet, and a method for producing the same. To provide a method for producing a hot-dip galvanized high-strength steel sheet in which superior workability and high strength are obtained and moreover satisfactory galvanizability is obtained when galvanizing is performed using facilities such as a continuous galvanizing line. <IMAGE>

IPC 1-7  
**C22C 38/00**; **C21D 9/46**; **C22C 38/04**; **C22C 38/12**; **C22C 38/14**; **C23C 2/02**; **C23C 2/06**; **C21D 8/04**

IPC 8 full level  
**C22C 38/04** (2006.01); **C22C 38/08** (2006.01); **C22C 38/12** (2006.01); **C22C 38/14** (2006.01); **C22C 38/16** (2006.01); **C23C 2/02** (2006.01); **C23C 2/28** (2006.01); **C21D 8/02** (2006.01); **C21D 8/04** (2006.01)

CPC (source: EP KR US)  
**C21D 8/0226** (2013.01 - KR); **C21D 8/0236** (2013.01 - KR); **C21D 8/0278** (2013.01 - KR); **C22C 38/04** (2013.01 - EP KR US); **C22C 38/06** (2013.01 - KR); **C22C 38/08** (2013.01 - EP KR US); **C22C 38/12** (2013.01 - EP KR US); **C22C 38/14** (2013.01 - EP KR US); **C22C 38/16** (2013.01 - EP KR US); **C23C 2/02** (2013.01 - EP KR US); **C23C 2/0224** (2022.08 - EP KR US); **C23C 2/024** (2022.08 - EP KR US); **C23C 2/28** (2013.01 - EP KR US); **C21D 8/0226** (2013.01 - EP US); **C21D 8/0273** (2013.01 - EP US); **C21D 8/0278** (2013.01 - EP US); **C21D 8/0478** (2013.01 - EP US); **C21D 2211/005** (2013.01 - EP KR US)

Citation (search report)

- [PX] PATENT ABSTRACTS OF JAPAN vol. 2000, no. 02 29 February 2000 (2000-02-29)
- [XA] PATENT ABSTRACTS OF JAPAN vol. 017, no. 468 (C - 1102) 26 August 1993 (1993-08-26)
- [XA] PATENT ABSTRACTS OF JAPAN vol. 017, no. 458 (C - 1100) 20 August 1993 (1993-08-20)
- [A] PATENT ABSTRACTS OF JAPAN vol. 1998, no. 12 31 October 1998 (1998-10-31)
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Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)  
**EP 1146132 A1 20011017**; **EP 1146132 A4 20020605**; **EP 1146132 B1 20070221**; AU 7685700 A 20010508; AU 773014 B2 20040513; CA 2353492 A1 20010503; CA 2353492 C 20041026; CN 1124358 C 20031015; CN 1341154 A 20020320; DE 60033498 D1 20070405; DE 60033498 T2 20071031; KR 100572179 B1 20060418; KR 20010080778 A 20010822; TW 521095 B 20030221; US 6537394 B1 20030325; WO 0131077 A1 20010503

DOCDB simple family (application)  
**EP 00966468 A 20001013**; AU 7685700 A 20001013; CA 2353492 A 20001013; CN 00804149 A 20001013; DE 60033498 T 20001013; JP 0007115 W 20001013; KR 20017007932 A 20010621; TW 89122204 A 20001020; US 86867401 A 20010621